



Dual Enclosure Liquid Cooling (DELC)

Chiller-less Data Centers with Liquid Cooled Servers To Enable Significant Data Center Energy Savings

Dr. Madhu Iyengar, Senior Engineer, STG Advanced Thermal Lab
December 13th 2011, Energy Efficiency HPC Working Group

Madhusudan Iyengar, Milnes David, Vinod Kamath, David Graybill,
Bejoy Kochuparambil, Robert Simons and Roger Schmidt.
IBM System and Technology Group (STG)

Timothy Chainer (PI), Michael Gaynes, Pritish Parida, Mark Schultz,
Arun Sharma, and Hien Dang.
IBM Research Division

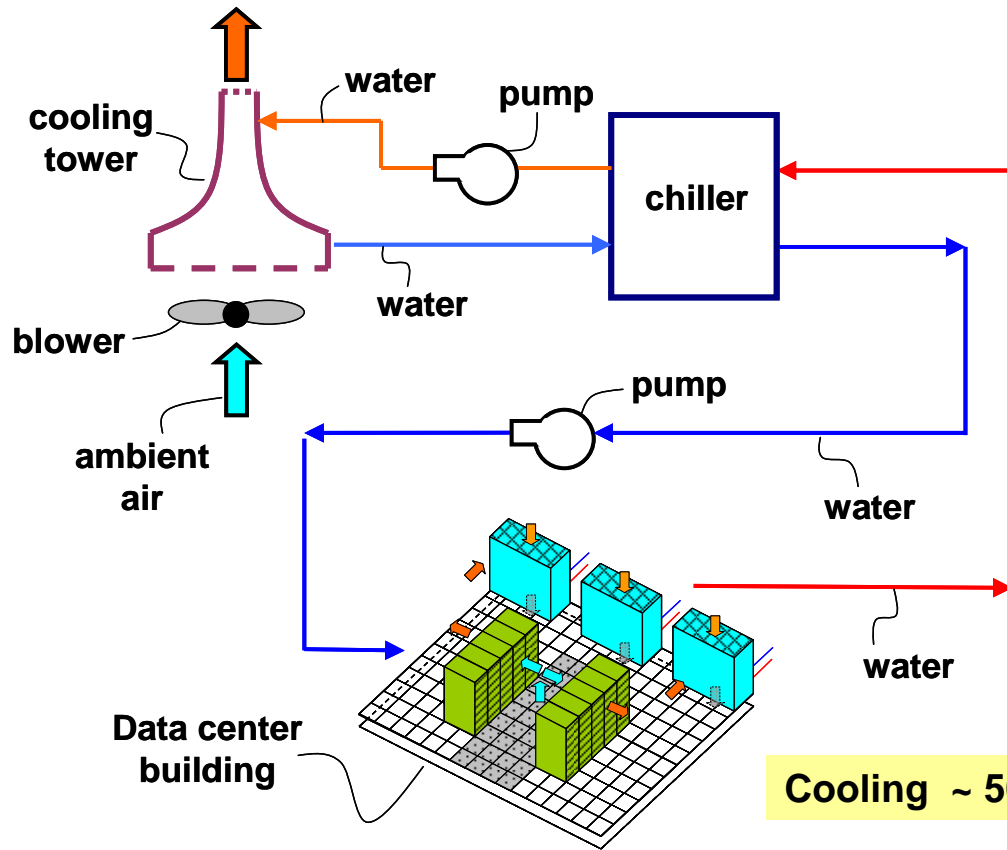
IBM Acknowledgements: Pok Site & Facilities/G&E (Donato Caferra, Sal Rosato, Joe Caricari, Tony “D”, Yun Lau, Chris), Pat Coico, James Steffes, Corey Vandeventer, Mark Steinke, Gerry Weber, Mike Ellsworth, James Whately, Brenda Horton, Yves Martin

Acknowledgements

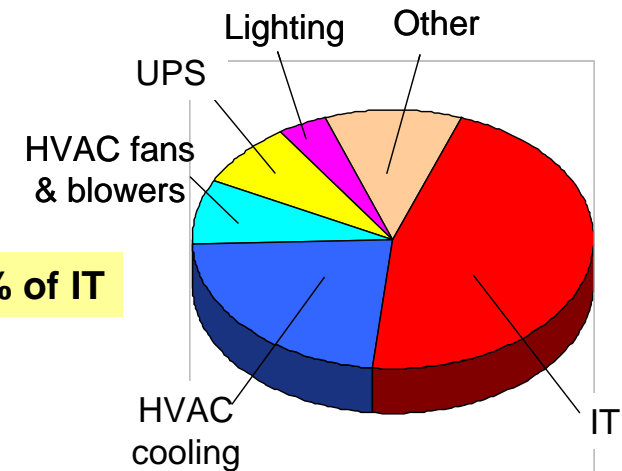
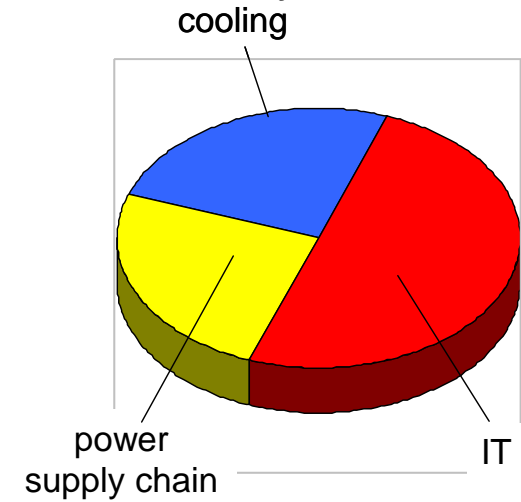
This project was supported in part by the U.S. Department of Energy's Industrial Technologies Program under the American Recovery and Reinvestment Act of 2009, award no. DE-EE0002894. We thank the DOE Project Officer Debo Aichbhaumik, DOE Project Monitors Darin Toronjo and Chap Sapp and DOE HQ Contact Gideon Varga for their support throughout the project.

Traditional data center cooling infrastructure

(b) 2009 Vision and Roadmap document by DoE



(a) Traditional data center facility



(c) ASHRAE book chart using LBNL case study data

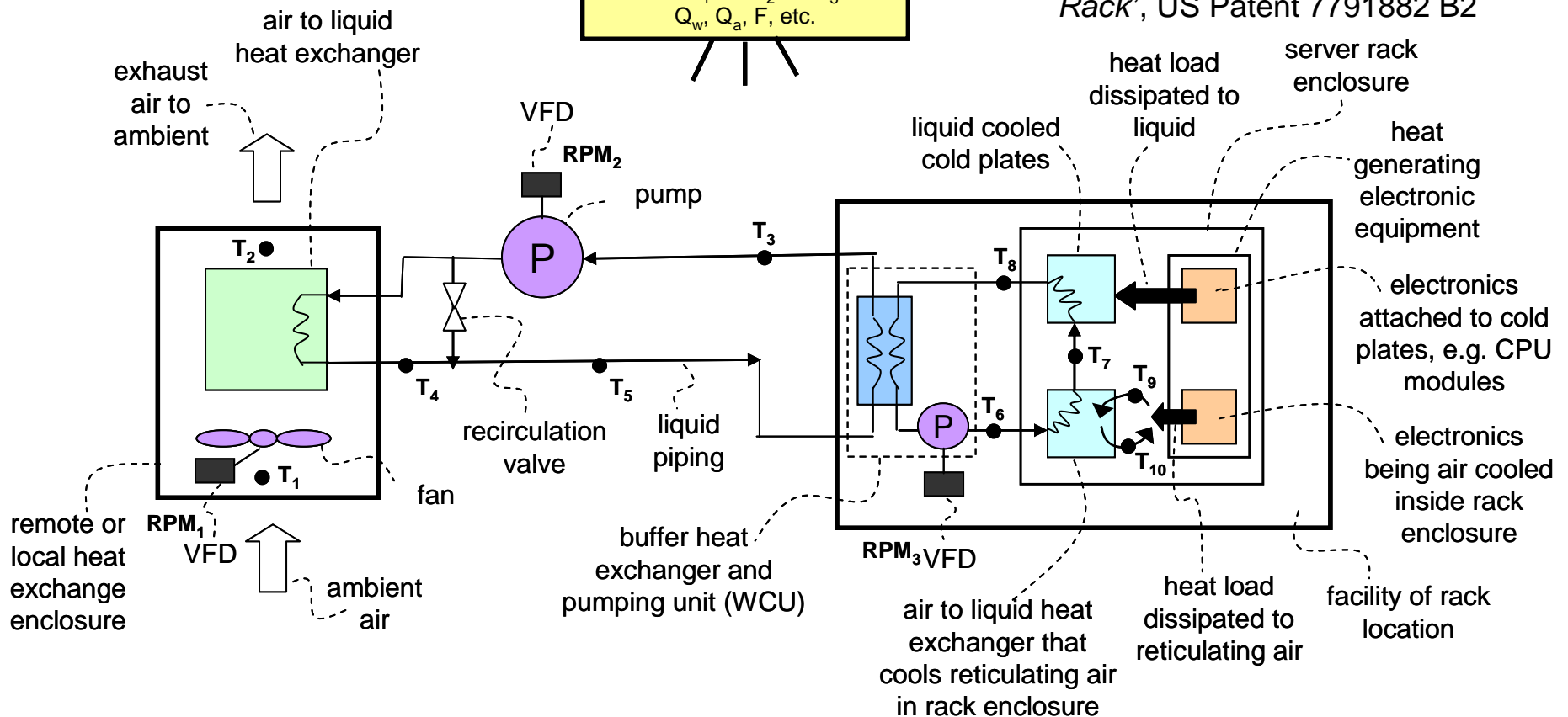
Goal is to reduce data center cooling energy use to 10% of IT & 5% of a typical data center energy

Innovative data center design

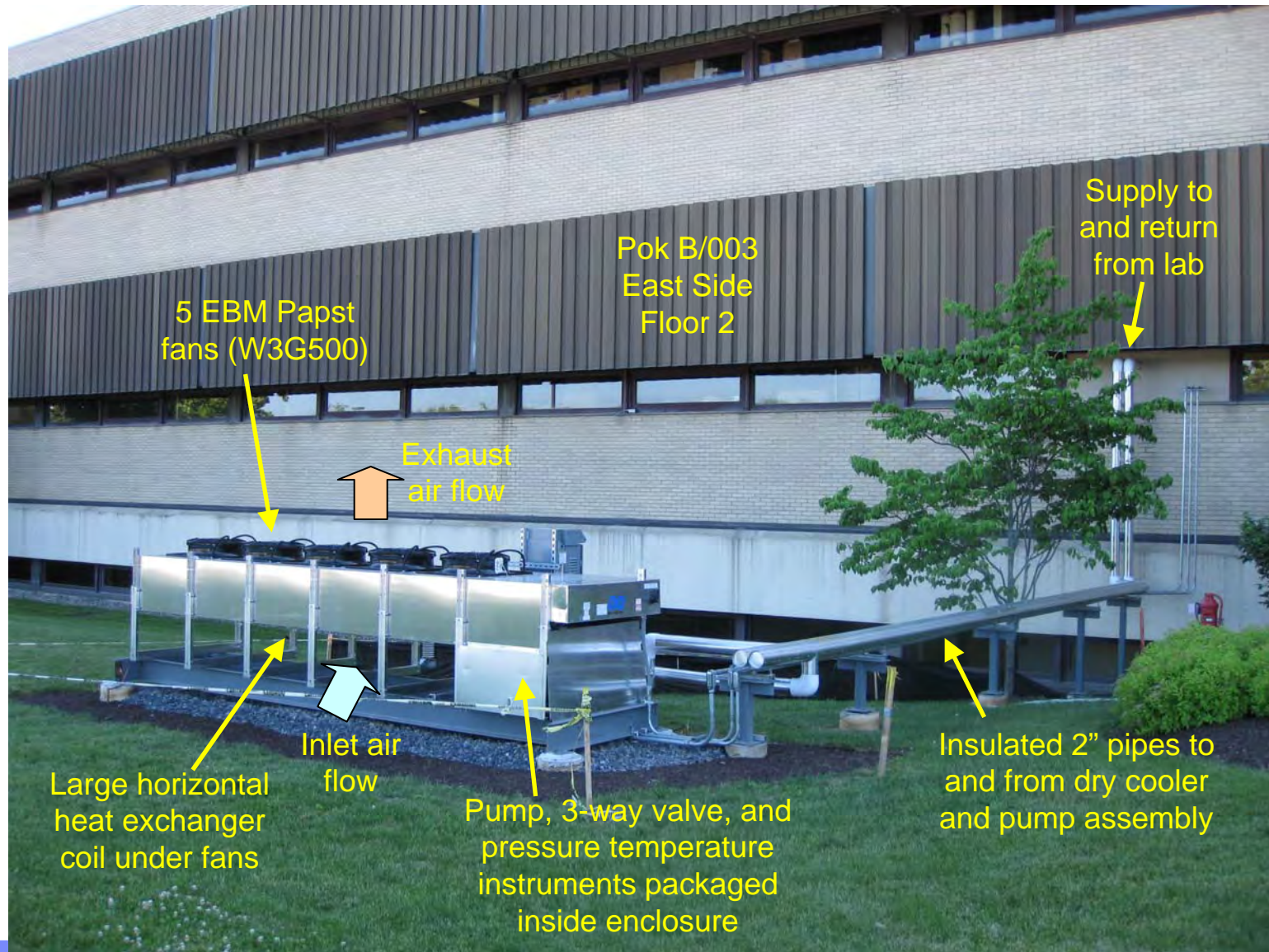
- Eliminate chillers and room air-conditioning.
- Reject heat to ambient using server liquid cooling.
- Reduce refrigerant and make up water usage.

Programmable Logic Control (PLC)
 Receiving data for
 $T_1, T_{10},$
 RPM_1, RPM_2, RPM_3
 $Q_w, Q_a, F,$ etc.

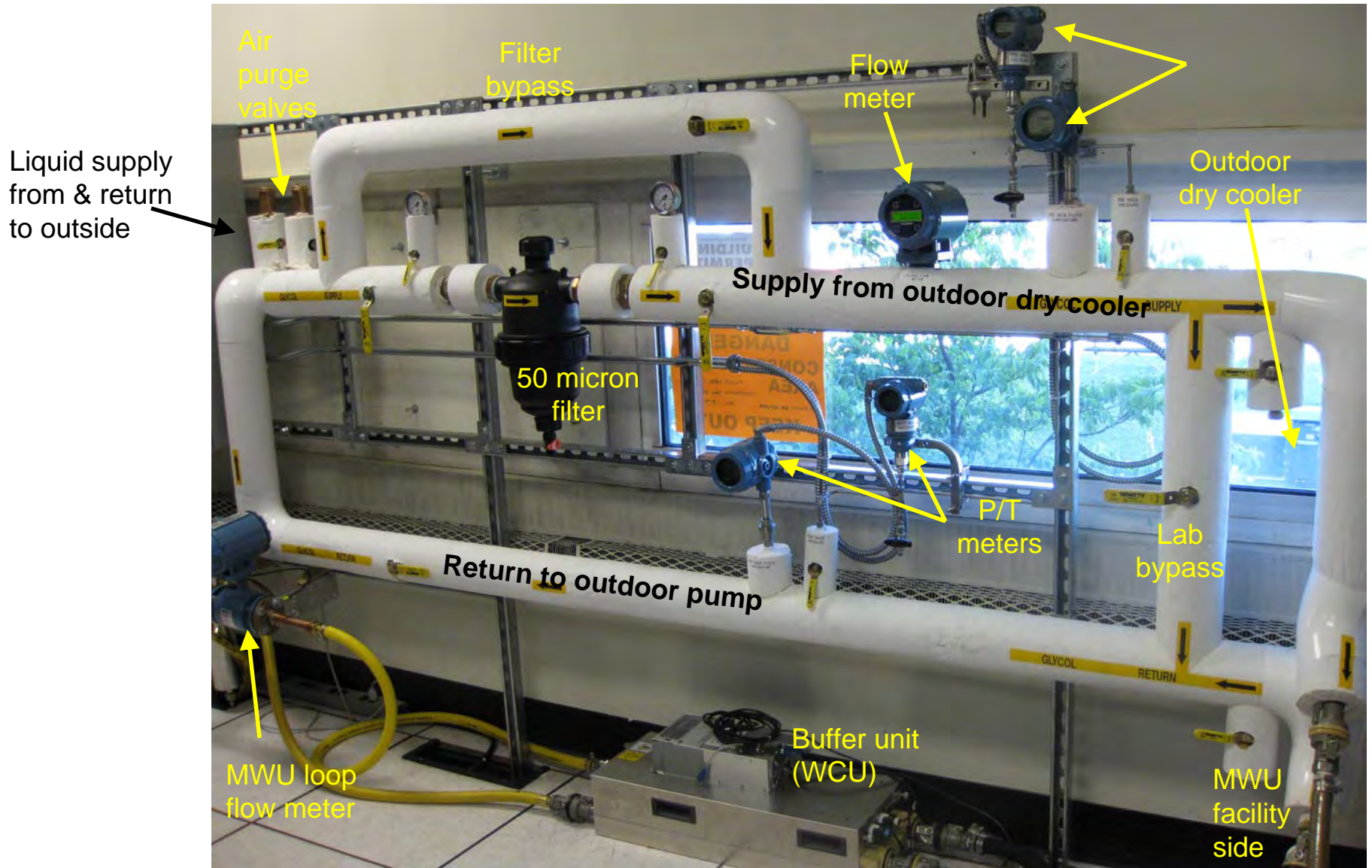
R. Chu, M. Iyengar, V. Kamath, and R. Schmidt, 2010, "Energy Efficient Apparatus and Method for Cooling an Electronics Rack", US Patent 7791882 B2



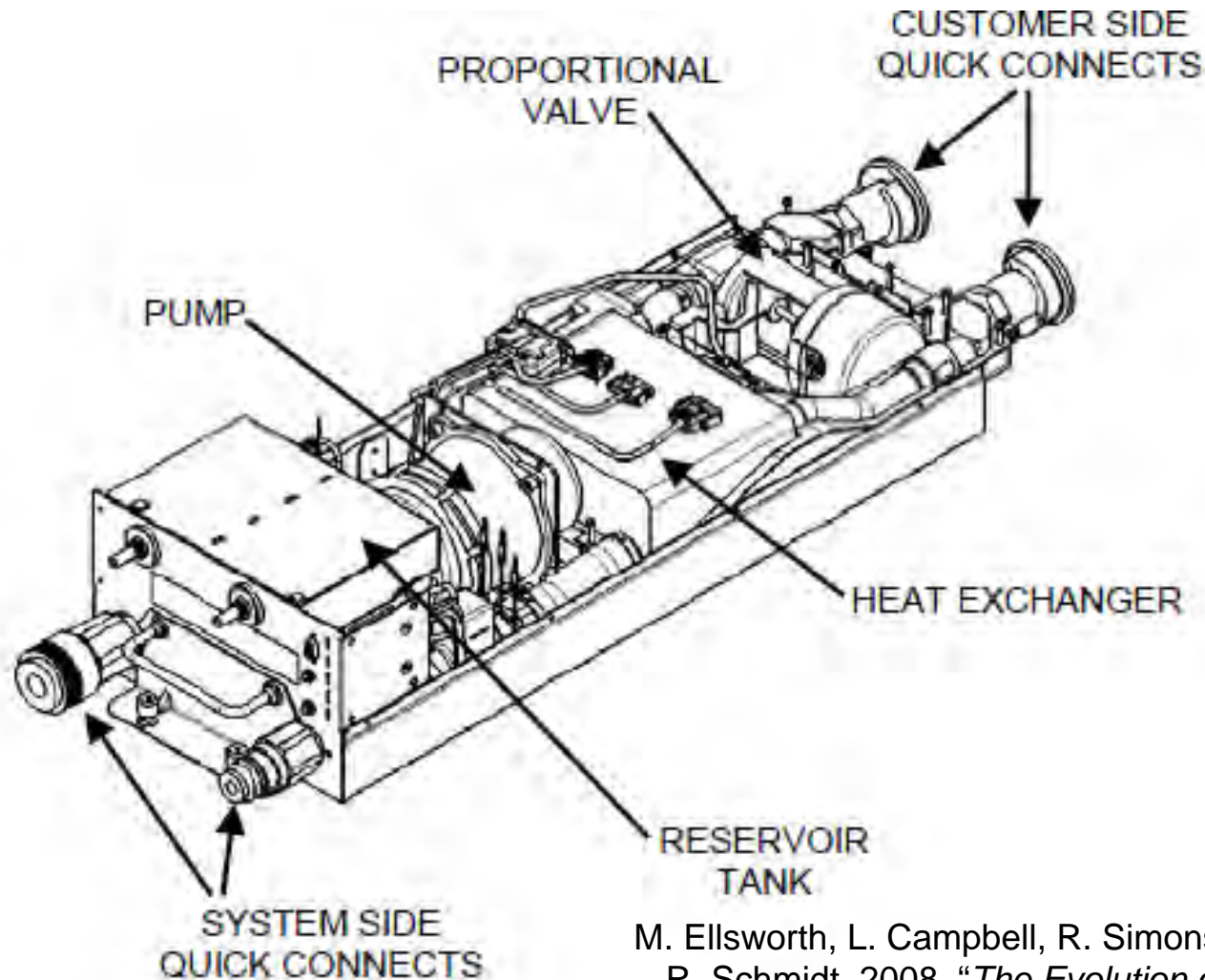
DOE outdoor loop layout (using a dry cooler to reject heat to the outdoor air)



Piping layout inside the lab



Water Cooling Unit (WCU) - Buffer unit



M. Ellsworth, L. Campbell, R. Simons, M. Iyengar, R. Chu, and R. Schmidt, 2008, "The Evolution of Water Cooling for IBM Large Server Systems: Back to the Future", Proceedings of the IEEE ITherm Conference in Orlando, USA, May.

Programmable Logic Control (PLC)

- Collects power/thermal data from data center loop devices.
- Controls external pump, external fan, and three-way valve (winter).
- Allows Labview full control or uses embedded control algorithm for robust operation.
- Takes over control in case of “safety” events.
- Can be turned on and directly used in PLC mode.
- Provides learning for integrating commercial strength BMS with rack level operation.



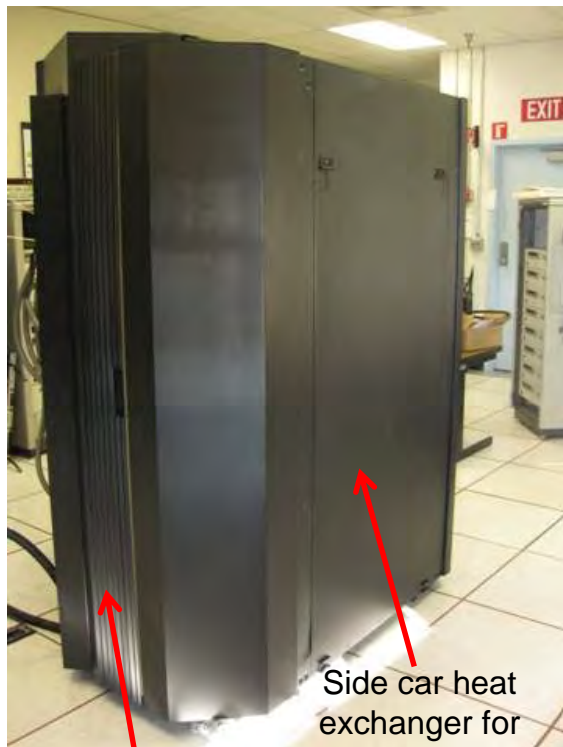
Rack level cooling design

- Cool servers using warm water and air supply.
- Totally (100%) liquid cooled at rack level.
- Advanced thermal interfaces in key locations.

R. Schmidt, M. Iyengar, D. Porter, G. Weber, D. Graybill, and J. Steffes, 2010, "Open Side Car Heat Exchanger that Removes Entire Server Heat Load Without any Added Fan Power", Proceedings of the IEEE ITherm Conference, Las Vegas, June.

U.S. Patent 6,775,137, "Method and Apparatus for Combined Air and Liquid Cooling of Stacked Electronic Components," R.C. Chu, M.J. Ellsworth, Jr., E. Furey, R.R. Schmidt, and R.E. Simons

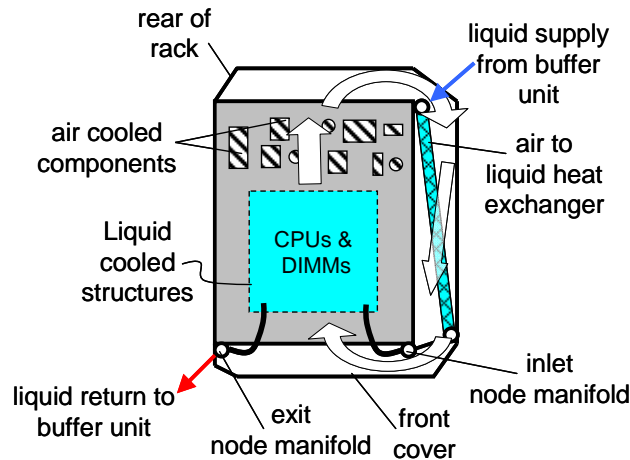
(a) Photograph of rack



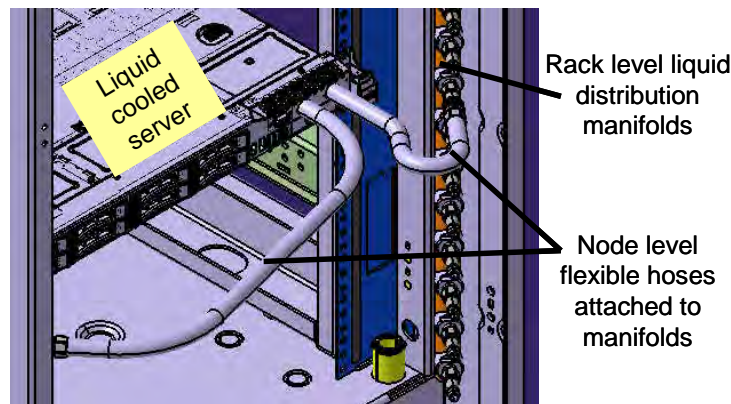
Front of Rack

Side car heat exchanger for cooling recirculating air from servers

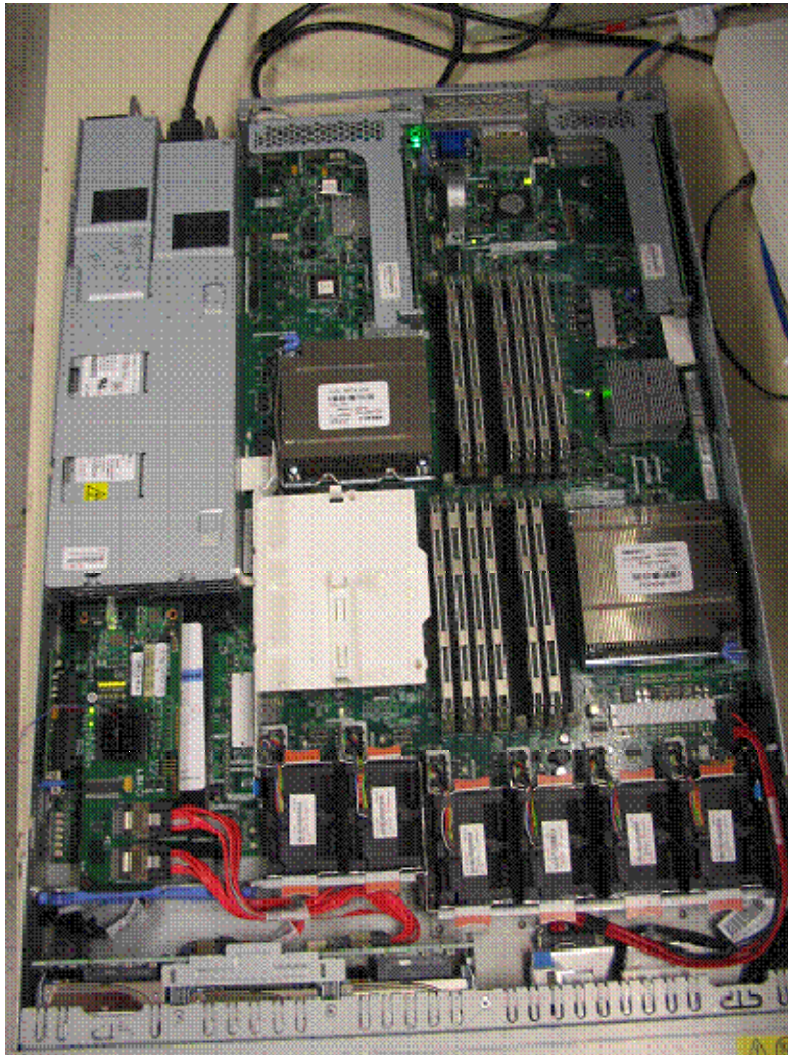
(b) Rack plan view schematic



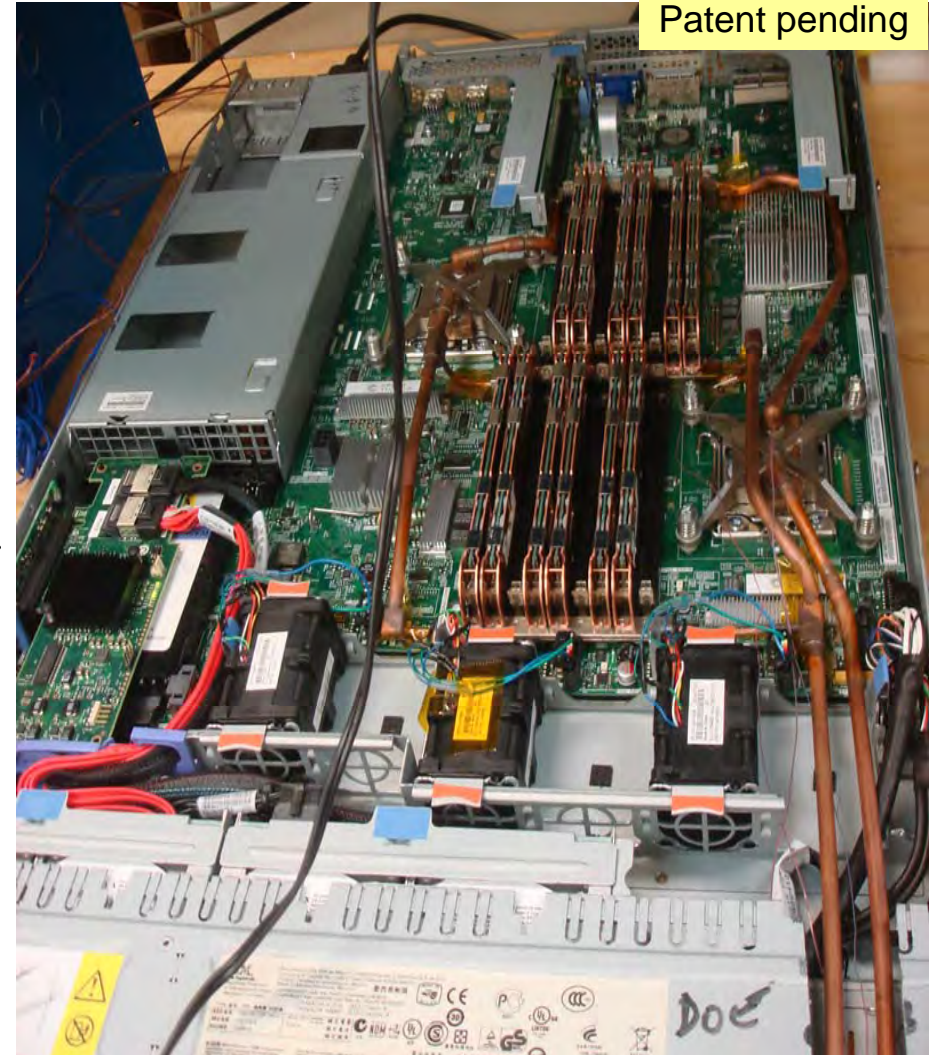
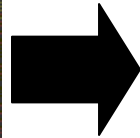
(c) Internal plumbing to liquid cooled node



IBM System X 1U server - x3550M3



Air cooled server

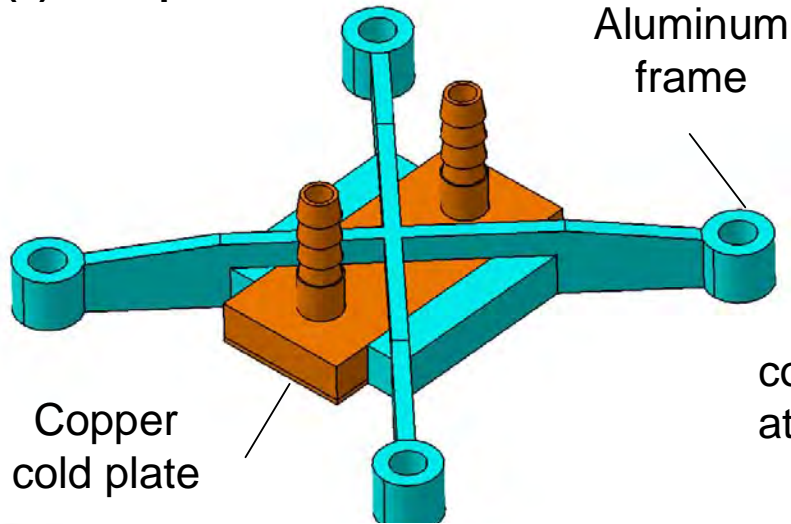


Water cooled server with CPU and DIMM liquid cooling w/ 3 fans

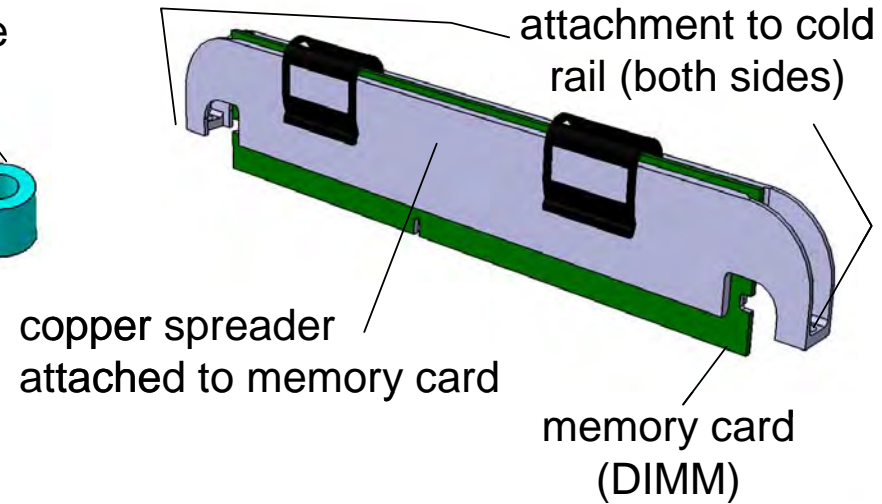
Server liquid cooling components

Patent pending

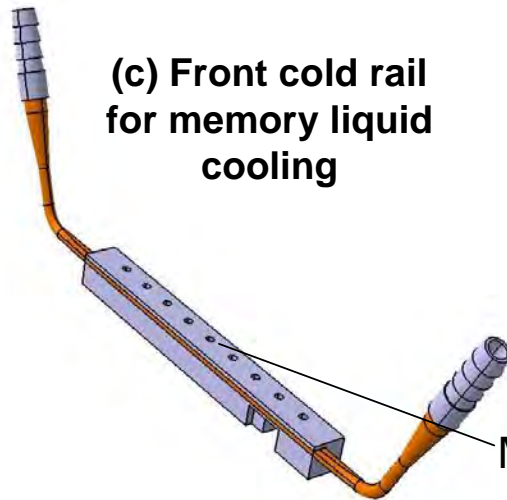
(a) Cold plate



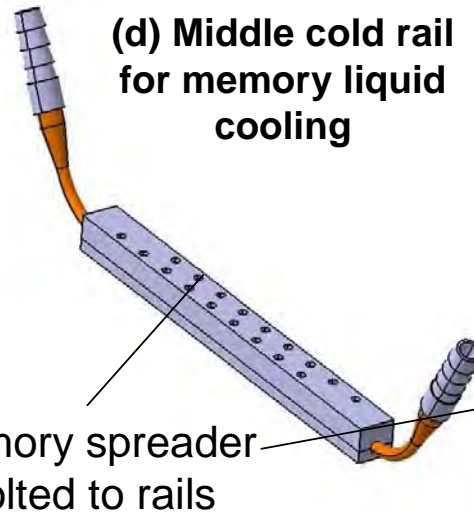
(b) Memory conduction spreader



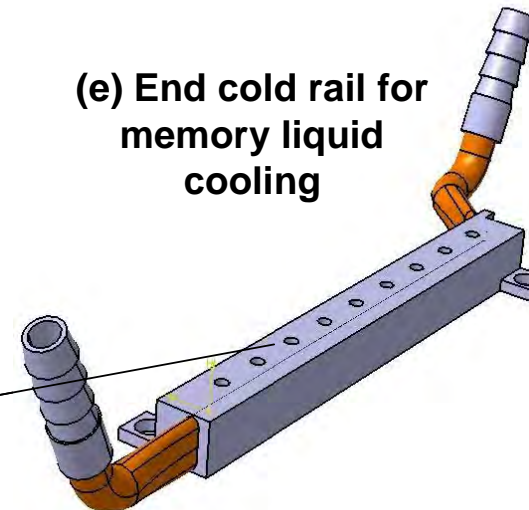
(c) Front cold rail for memory liquid cooling



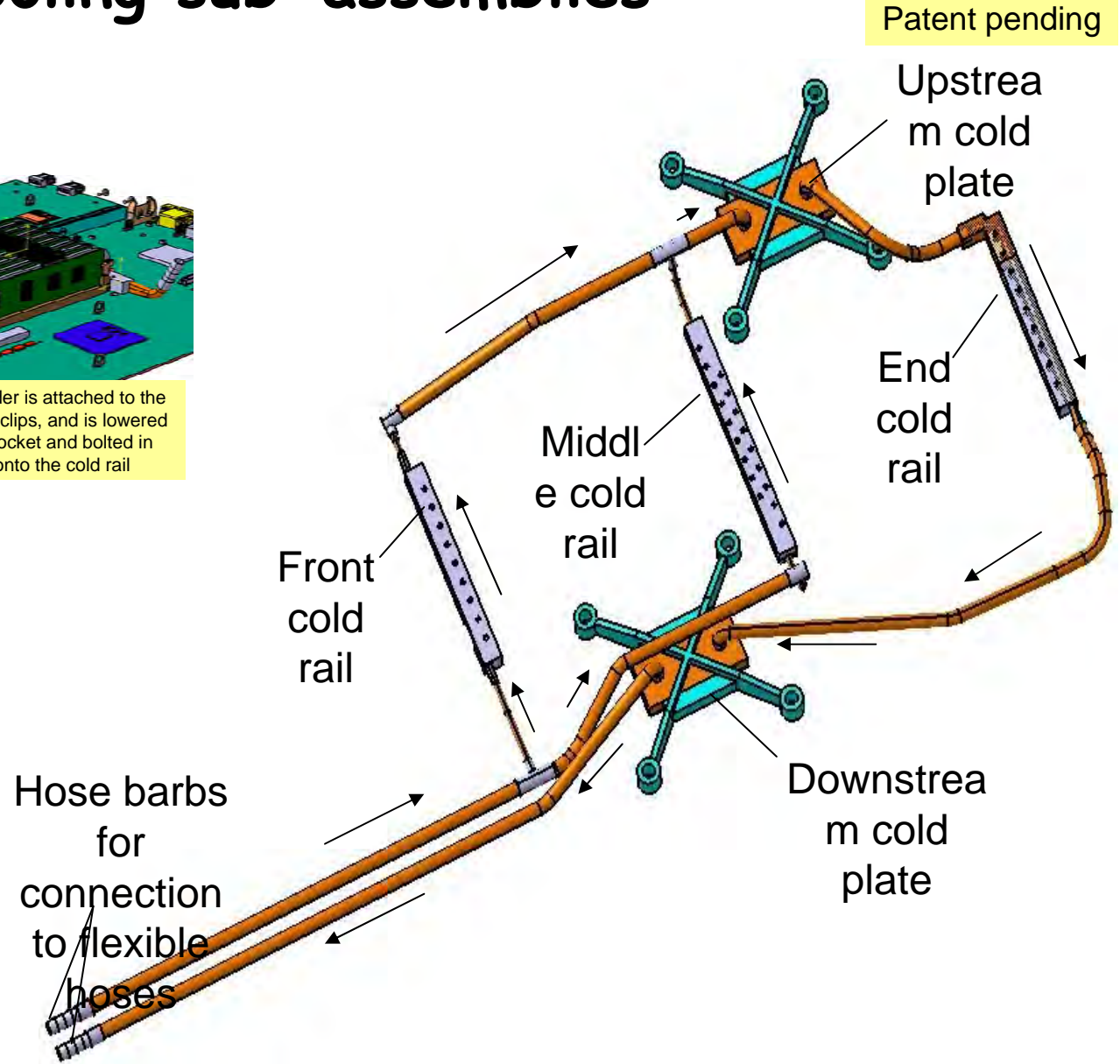
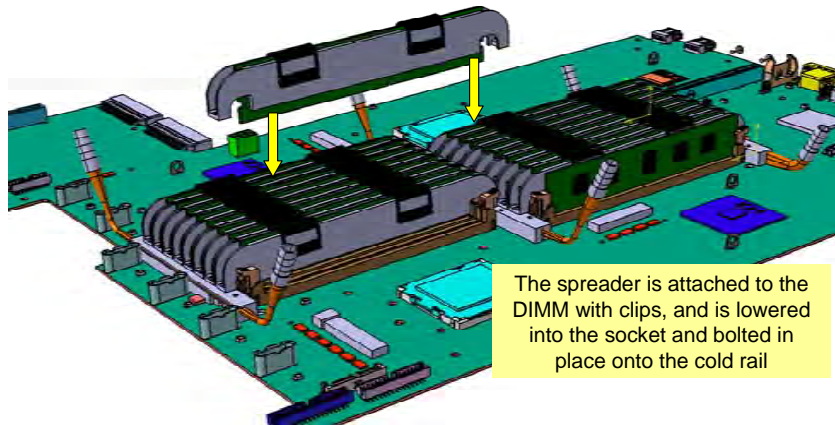
(d) Middle cold rail for memory liquid cooling



(e) End cold rail for memory liquid cooling



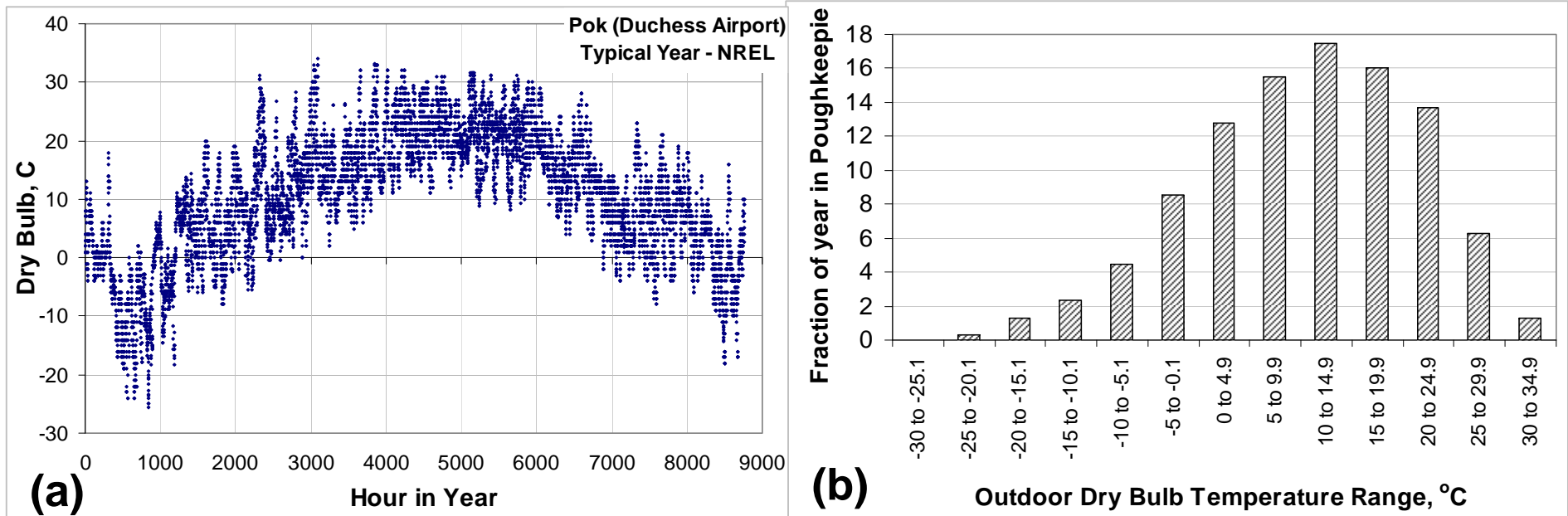
Server liquid cooling sub-assemblies



Thermal chamber test for air/liquid cooled servers

<p style="text-align: center;">CASE A</p> <p><u>“Cool” air cooled node</u></p> <ul style="list-style-type: none"> ▪ 25.3°C inlet air temperature ▪ Exerciser setting at 90% ▪ 12 fans running at 7242 rpm (avg.) ▪ System power = 395 W ▪ Fan power = 19.1 W ▪ CPU lid temps. = 65.3 °C, 74 °C ▪ DIMM temperatures = 35-46 °C ▪ 12 x 8 GB DIMMS 	<p style="text-align: center;">CASE B</p> <p><u>“Hot” air cooled node</u></p> <ul style="list-style-type: none"> ▪ 35.4°C inlet air temperature ▪ Exerciser setting at 90% ▪ 12 fans running at 11978 rpm (avg.) ▪ System power = 423 W ▪ Fan power = 56.8 W ▪ CPU lid temps. = 68.9 °C, 71.9 °C ▪ DIMM temperatures = 35-46 °C ▪ 12 x 8 GB DIMMS
<p style="text-align: center;">CASE C</p> <p><u>“Hot” water cooled node</u></p> <ul style="list-style-type: none"> ▪ 49.9 °C inlet air temperature ▪ 45.2 °C inlet water temperature ▪ Exerciser setting at 90% ▪ 3 fans running at 12612 rpm (avg) ▪ System power = 411 W ▪ Fan power = 30.9 W ▪ CPU lid temps. → 62.8°C, 61.9°C ▪ DIMM temperatures → 53-56 °C ▪ 12 x 8 GB DIMMS 	<p style="text-align: center;">CASE D</p> <p><u>“Cool” water cooled node</u></p> <ul style="list-style-type: none"> ▪ 24.9 °C inlet air temperature ▪ 20.1 °C inlet water temperature ▪ Exerciser setting at 90% ▪ 3 fans running at 5838 rpm (avg) ▪ System power = 354 W ▪ Fan power = 8.3 W ▪ CPU lid temps. → 36.8°C, 35.9°C ▪ DIMM temperatures → 28-33 °C ▪ 12 x 8 GB DIMMS

Typical Poughkeepsie weather data (NREL)



Experimental data for 22 h test (August 2011)



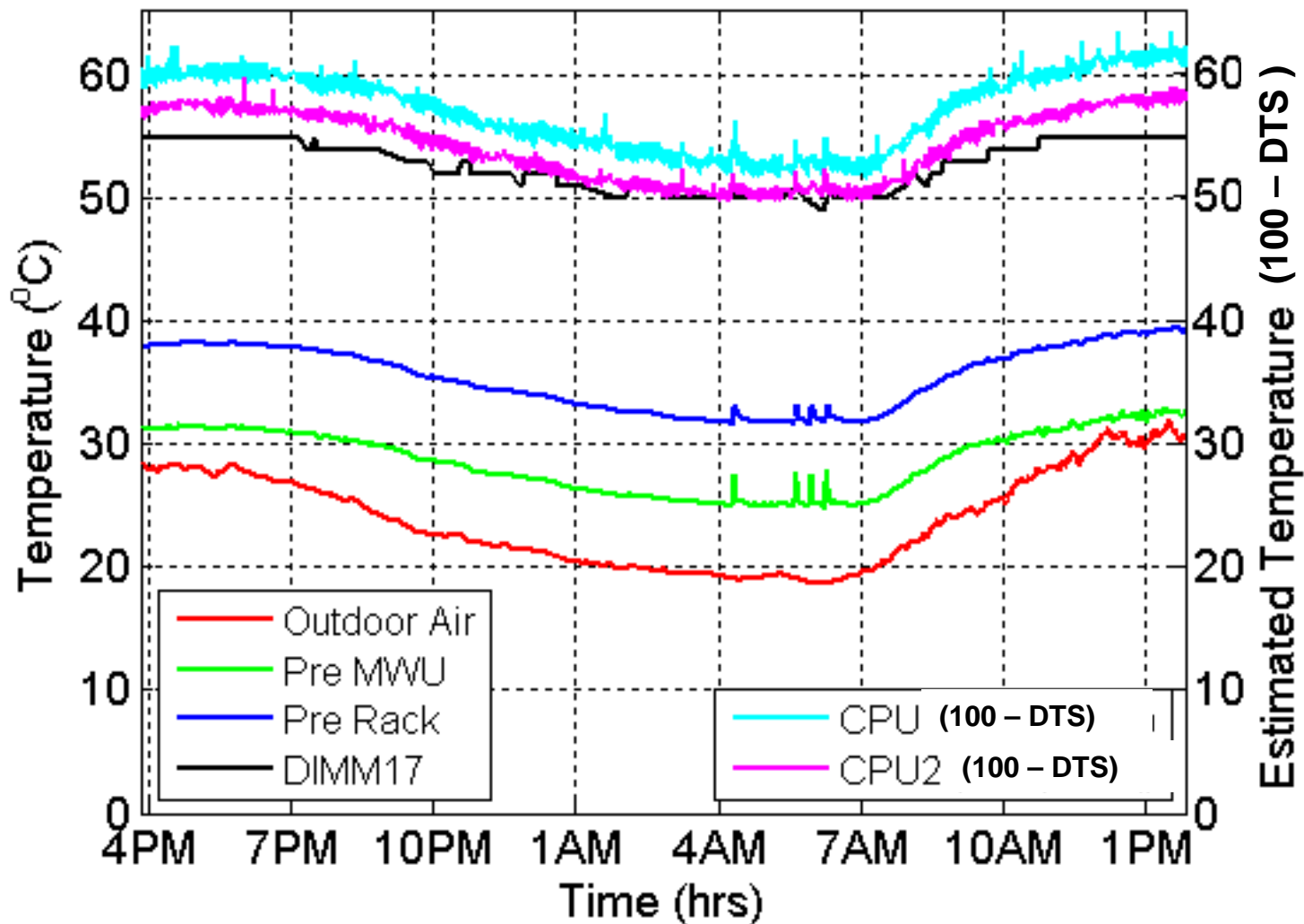
Total data center cooling power is less than 3.5% of IT for a hot NY summer day

Date Stamp	Time Stamp	Ave. outside air temp C	Ave. IT Power kW	Ave. Cooling Power kW	Cooling power as % of IT	Ave. server inlet air temp C	Ave. rack inlet water temp C
8/4/2011	4:00:30 PM	28.1	13.43	0.440	3.28	38.1	36.3
8/4/2011	4:59:56 PM	28.1	13.47	0.442	3.28	38.5	36.4
8/4/2011	6:00:22 PM	27.9	13.50	0.441	3.27	38.6	36.4
8/4/2011	7:00:54 PM	27.3	13.48	0.440	3.26	38.5	36.2
8/4/2011	8:01:25 PM	26.3	13.43	0.433	3.23	38.2	35.8
8/4/2011	9:01:54 PM	24.9	13.36	0.433	3.24	37.7	35.2
8/4/2011	10:02:17 PM	23.2	13.22	0.438	3.31	36.9	34.2
8/4/2011	11:02:41 PM	22.4	13.09	0.437	3.33	36.2	33.3
8/5/2011	12:03:04 AM	21.7	12.99	0.439	3.38	35.5	32.6
8/5/2011	1:03:27 AM	20.9	12.96	0.440	3.39	35.1	32.0
8/5/2011	2:03:49 AM	20.2	12.88	0.443	3.44	34.6	31.2
8/5/2011	3:04:12 AM	19.8	12.81	0.441	3.44	34.3	30.8
8/5/2011	4:04:34 AM	19.4	12.77	0.442	3.46	34.0	30.4
8/5/2011	5:04:58 AM	19.1	12.76	0.443	3.47	33.9	30.3
8/5/2011	6:05:24 AM	19.0	12.76	0.448	3.51	33.8	30.4
8/5/2011	7:05:46 AM	19.0	12.77	0.440	3.45	33.9	30.4
8/5/2011	8:06:10 AM	20.8	12.79	0.437	3.41	34.3	31.1
8/5/2011	9:06:41 AM	23.3	13.01	0.432	3.32	35.8	33.3
8/5/2011	10:07:10 AM	25.0	13.21	0.432	3.27	37.2	35.0
8/5/2011	11:07:40 AM	27.4	13.37	0.437	3.27	38.0	35.9
8/5/2011	12:08:12 PM	29.1	13.48	0.449	3.33	38.6	36.6
8/5/2011	1:08:44 PM	30.5	13.58	0.465	3.43	39.3	37.3
8/5/2011	1:55:08 PM	31.0	13.58	0.477	3.51	39.5	37.6

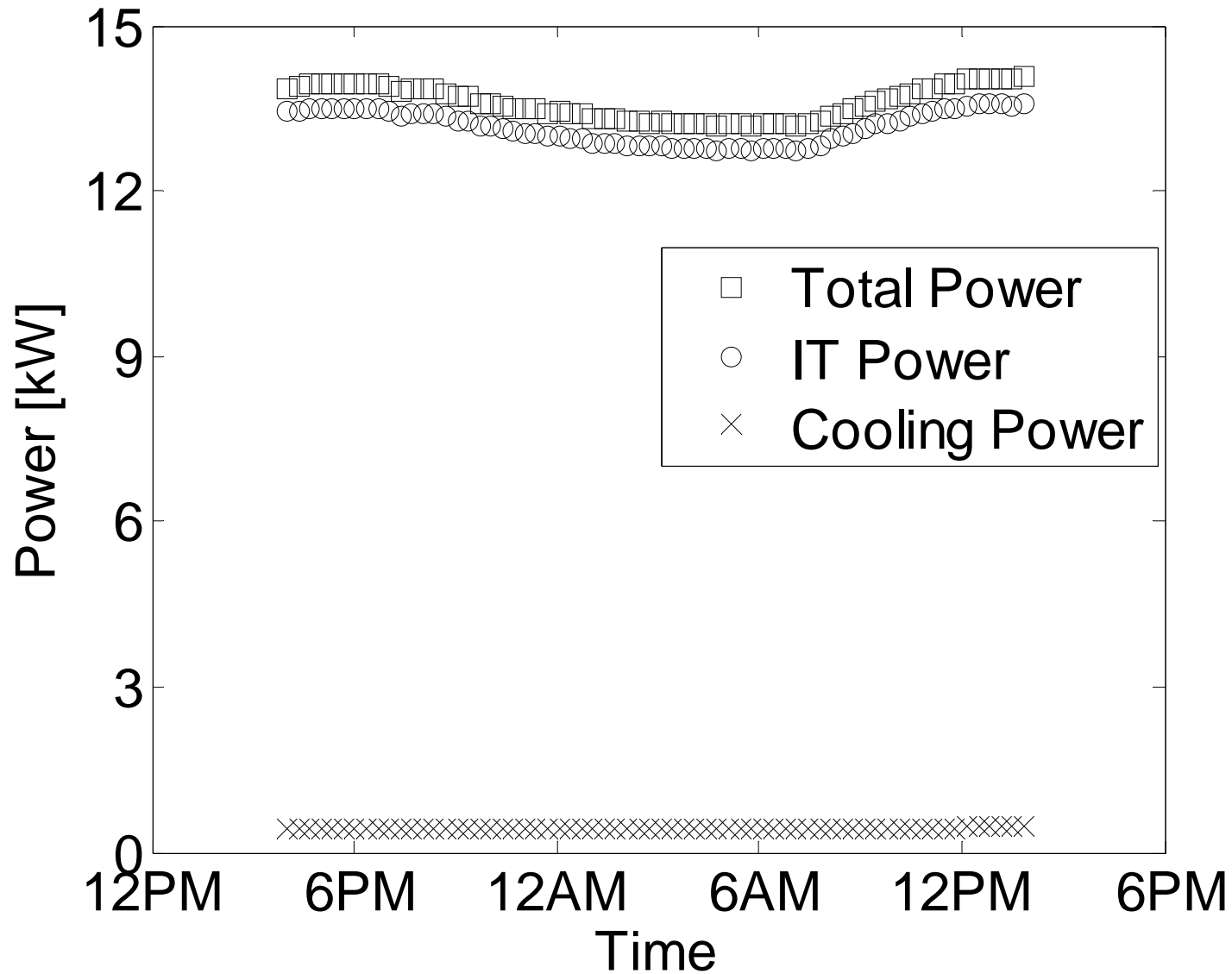
Temperature data for 22 h test (August 2011)



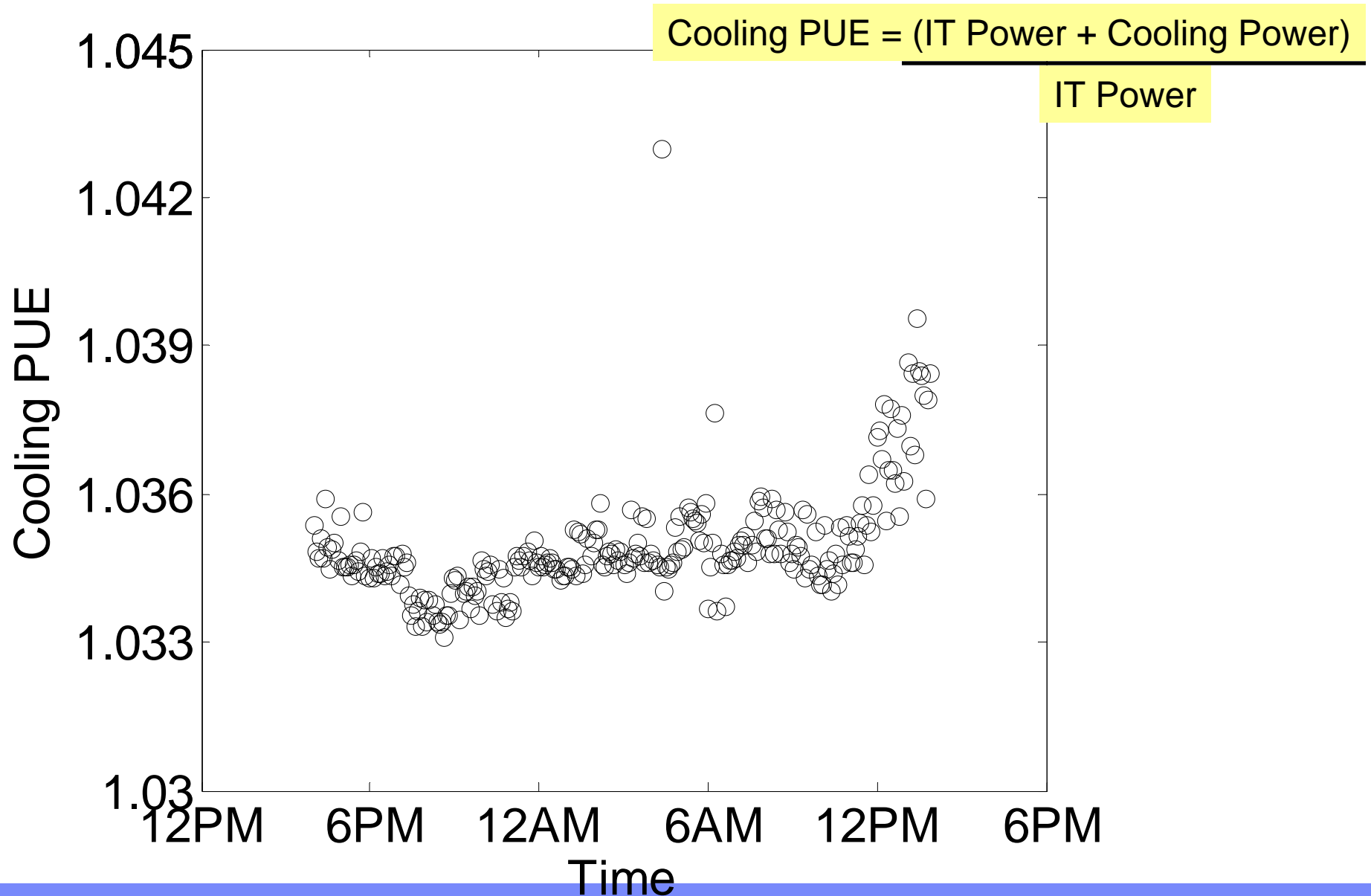
Total data center cooling power is 3.5% of IT for a hot NY summer day



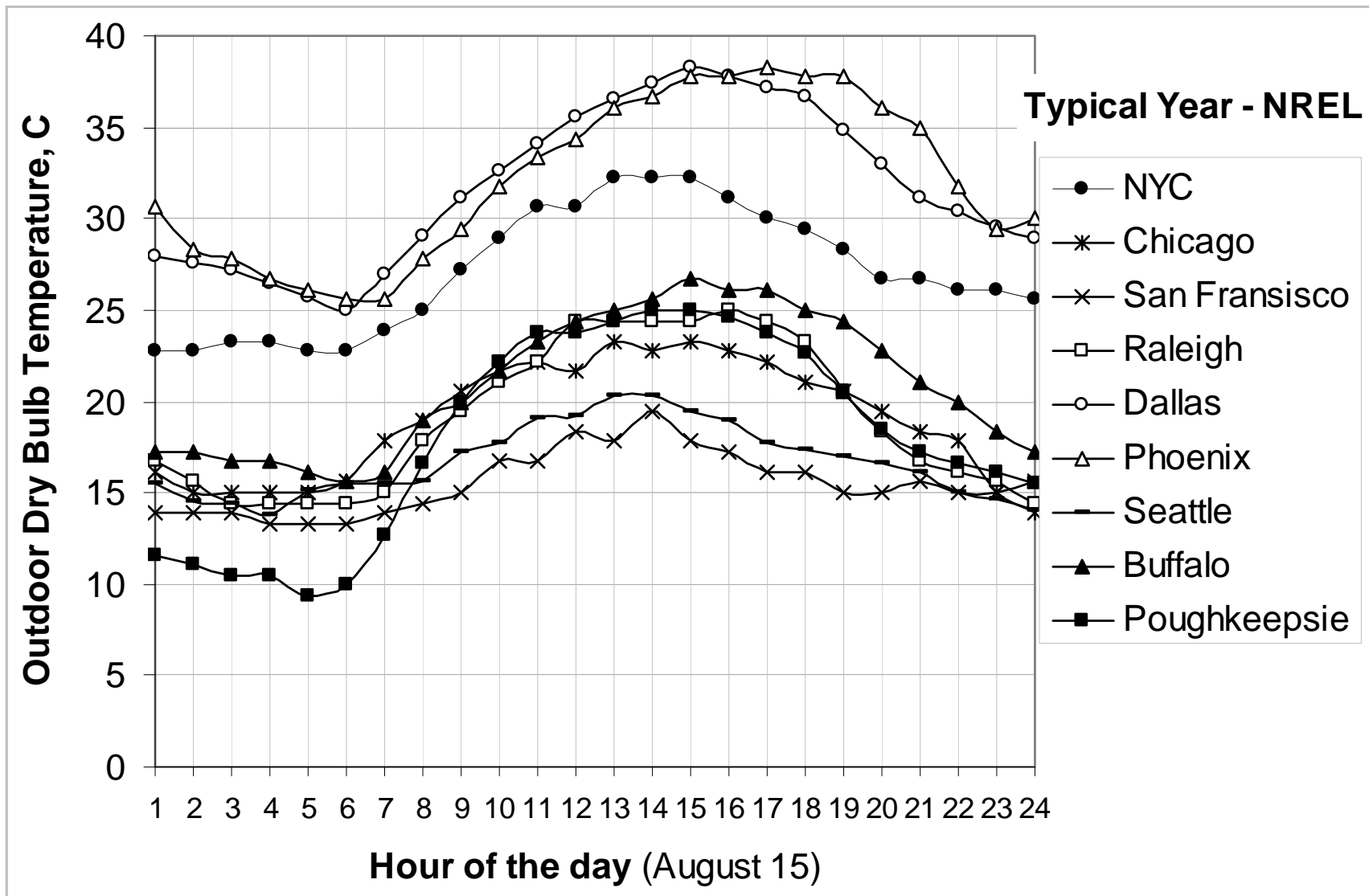
Power data for 22 h test



Cooling PUE data for 22 h test (August 2011)



Analyses for 9 US cities for a summer day



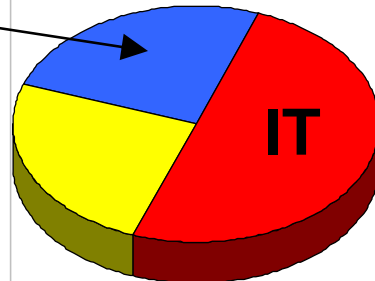
Energy and energy cost savings 9 US cities for a summer day 1000 kW IT load, Aug 15 ave.

<http://www.electricchoice.com/electricity.prices-by-state.php>
2010 Industrial rate assumed

	Typical data center cooling, kW	DELTC based data center cooling, kW	Energy Savings, kWh	Local cost of electricity, \$/kWh	Energy cost savings, \$
New York City	500	20.7	11504	0.0973	1119.3
Chicago	500	15.4	11631	0.075	872.3
San Francisco	500	15.0	11640	0.1078	1254.8
Raleigh	500	15.6	11625	0.0613	712.6
Dallas	500	31.5	11243	0.0658	739.8
Phoenix	500	32.5	11220	0.0674	756.2
Seattle	500	15.0	11640	0.0396	460.9
Buffalo	500	16.0	11617	0.0973	1130.3
Poughkeepsie	500	15.5	11627	0.0973	1131.3

50% of IT power

DoE 2009 Vision and Roadmap document



**Less than 3.5%
of IT power**

IBM warm water cooled cluster - 2012

Press room > Press releases >

Leibniz Supercomputing Centre Selects IBM Supercomputer Equipped with Next Generation Intel® Xeon® Processors to Support Ultra-challenging Research

Innovative hot-water cooled supercomputer to deliver up to three petaflops of peak performance when online in 2012

↓ Press release

↓ Contact(s) information

↓ Related XML feeds

Garching/Munich/Stuttgart, Germany - 13 Nov 2010: The Leibniz Supercomputing Centre (LRZ) in Garching, Germany has signed a contract with IBM (NYSE: [IBM](#)) to develop and build a new general purpose supercomputer with next generation Intel® Xeon® processors to support advanced scientific research. The system will use i consume 40 percent less energy than a comparab

Named "SuperMUC", the new system is part of the Europe (PRACE) HPC infrastructure for researcher Europe. It will enable LRZ's scientific community to predict outcomes as never before. The supercomp federal government and the state of Bavaria.

I. Meijer, 2011, "Hot Water Cooling for Energy-Hungry Datacenters".

- Highly energy-efficient hybrid-cooling solution:
 - Compute racks
 - 90% Heat flux to warm water
 - 10% Heat flux to CRAH
 - Switch / Storage racks
 - Rear door heat exchangers
- Compute node power consumption reduced ~ 10% due to lower component temperatures and no fans.
- Power Usage Effectiveness P_{Total} / P_{IT} : PUE ~ 1.1
- Heat recovery is enabled by the compute node design.
- Energy Reuse Effectiveness $(P_{Total} - P_{Reuse}) / P_{IT}$: ERE ~ 0.3

IBM warm water cooled servers - 2012



Ref.: I. Meijer, SC11, “*Hot Water Cooling for Energy-Hungry Datacenters*”.

- Heat flux > 90% to water; very low chilled water requirement
- Power advantage over air-cooled node: warm water cooled ~10% (cold water cooled ~15%) due to lower $T_{\text{components}}$ and no fans.
- Typical operating conditions: $T_{\text{air}} = 25 - 35^{\circ}\text{C}$, $T_{\text{water}} = 18 - 45^{\circ}\text{C}$

Thank you

Q&A

Madhu Iyengar

mki@us.ibm.com

845-433-3708